



US008691043B2

(12) **United States Patent**
Sampica et al.

(10) **Patent No.:** **US 8,691,043 B2**
(45) **Date of Patent:** **Apr. 8, 2014**

(54) **SUBSTRATE LAMINATION SYSTEM AND METHOD**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 1386 days.

(21) Appl. No.: **12/009,375**

(22) Filed: **Jan. 18, 2008**

(65) **Prior Publication Data**

US 2009/0120572 A1 May 14, 2009

Related U.S. Application Data

(63) Continuation-in-part of application No. 11/214,518, filed on Aug. 30, 2005, now Pat. No. 7,566,254, and a continuation of application No. 11/215,683, filed on Aug. 30, 2005, now Pat. No. 7,435,311.

(51) **Int. Cl.**
B32B 37/00 (2006.01)

(52) **U.S. Cl.**
USPC **156/286; 156/285**

(58) **Field of Classification Search**
USPC 156/285, 286, 104, 106, 382
See application file for complete search history.

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(57) **ABSTRACT**

The present disclosure is directed to a substrate lamination system and method. A method for laminating substrates may comprise: (a) disposing a pressure-sensitive adhesive later between a substantially planar surface of a first substrate and a substantially planar surface of a second substrate; (b) disposing the first substrate, pressure-sensitive adhesive layer and second substrate within a vacuum chamber; (c) evacuating the vacuum chamber; (d) applying pressure to at least one of the first substrate and the second substrate. A system for laminating substrates may comprise: (a) means for disposing a pressure-sensitive adhesive layer between a substantially planar surface of a first substrate and a substantially planar surface of a second substrate; (b) means for disposing the first substrate, pressure-sensitive adhesive layer and second substrate within a vacuum chamber; (c) means for evacuating the vacuum chamber; (d) means for applying pressure to at least one of the first and second substrates.

26 Claims, 18 Drawing Sheets

